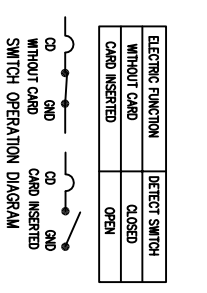
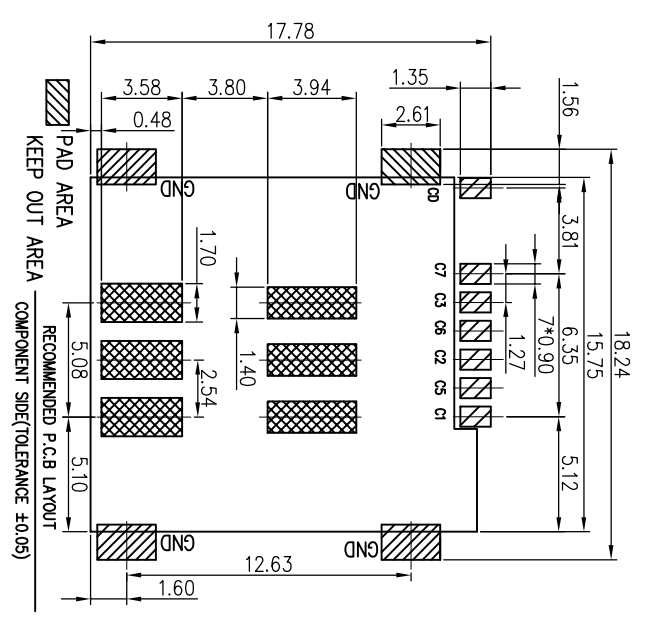


NOTES:
 1. SPECIALTY:
 1.1 Rated current: 1.0A
 1.2 Rated voltage: 30V
 1.3 Contact Resistance: 50mΩ MAX
 1.4 Insulation Resistance: 1000MΩ MIN 500V DC
 1.5 Dielectric withstanding voltage: 500V AC
 1.6 Solder ability: 250±5°C, 5±0.5s
 1.7 Durability: 1500 Cycles Min.
 1.8 Operating condition: Temperature: -40°C~+85°C;
 Humidity 80% RH MAX



MicroSIM CARD	Pin No.	NAME
C1	VCC	RST
C2	RST	CLK
C3	CLK	Reserved
C4	Reserved	GND
C5	GND	VPP
C6	VPP	I/O
C7	I/O	Reserved
C8	Reserved	



NO	Description	dosage	Material	Color/plating
1	Housing	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
2	Data Contact	1PC	COPPER ALLOY	CONTACT AREA: GOLD PLATED
3	CD Switch	1PC	COPPER ALLOY	CONTACT AREA: GOLD PLATED
4	Snell	1PC	STEEL	SMT AREA: GOLD PLATED
5	Slide	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
6	SPRING	1PC	SMP-B	PLATE WITH NICKEL
7	LINK	1PC	STEEL	PLATE WITH NICKEL

XNT 深圳市鑫南天科技有限公司
 Shenzhen XinNanTian Technology Co., Ltd

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A0	19/10/09	NEW		

OPERATION	DESIGN	CHECK	APPROVE
0.00 ±0.20			
0.0 ±0.30			
0 ±0.50			
Angle ± 3°			
DIM ± 0.10			

SCALE	UNIT	PART NO.	TITLE:	DRAWING NO.
1:1	mm	XNT-SMT50-007	MICRO SIM PUSH HL.5 6+1PIN	